

Halogen Free and Low Transmission Loss Multilayer Material for Next Generation High Speed Applications: “MCL-LW-900G/910G”

Masayuki Nakano Keita Johno Toshiyuki Iijima

Laminate Materials R&D Dept.,
Advanced Performance Materials R&D Division,
Advanced Performance Materials Business Headquarters

1 Abstract

The information communication terminal devices using communication networks are advancing transmission capacity and speed. As a result, the transmission speed of the network devices also is becoming faster. So, high-speed and high-frequency response of the PWB is also indispensable. Especially in the high-speed digital field, the demand for PWB material with excellent high frequency characteristics than the PWB materials of current low-transmission-loss is increasing¹⁾. In this situation, we have developed a new halogen-free low transmission loss material “MCL-LW-900G” for next generation high-speed networks.

2 Characteristics of MCL-LW-900G/910G

- Unique characteristics that can contribute to the reduction of transmission loss.
- High heat resistance and high glass transition temperature (T_g).
- Environmentally compliant material incorporating halogen-free flame retardant.

3 Background of the development

In recent years as shown in **Figure 1**, transmission capacity, transmission speed and frequency of digital signals handled by information and communication electronics equipment such as computers, servers and routers have become larger, faster and higher, respectively. In response to such technical trends, it is crucial to change the functional performance of printed circuit boards used in such equipment to meet the requirements of high-speed high-frequency communications. So far, our company has introduced MCL-FX-2 and several other multilayer materials used for high-frequency applications.

Under such circumstances, the transmission rate of digital signals handled by network communication equipment for next-generation high-speed applications may come down to 25 Gbps. To satisfy this transmission rate, we estimated a parameter of high-frequency property to be D_f of 0.0035 (at 10 GHz) or less from market requirements, but functional performance of conventional base materials are not good enough to satisfy such D_f. Against such a background, we developed base materials that can

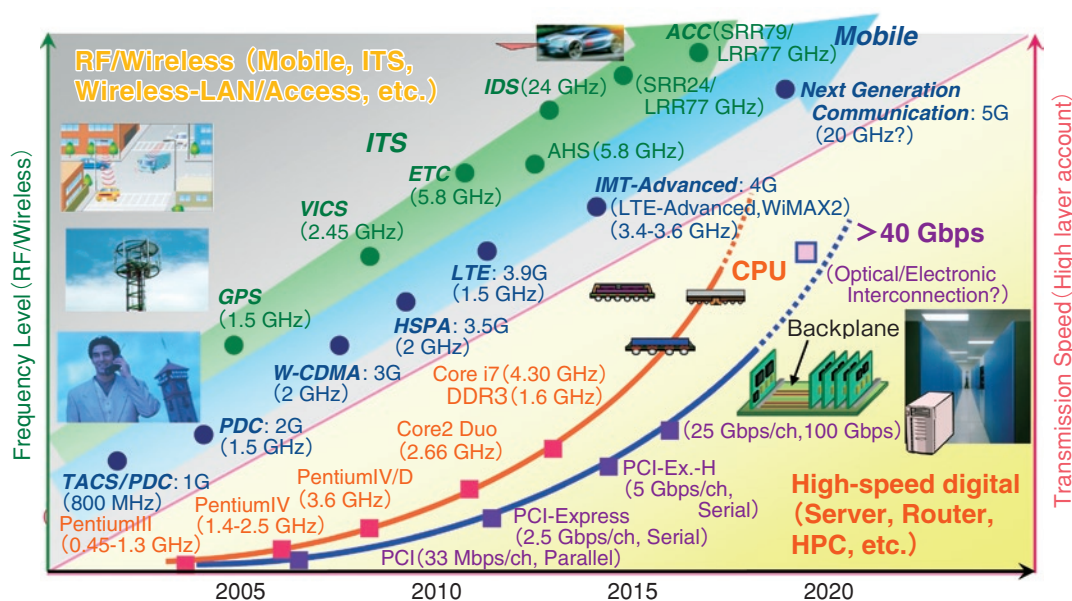


Figure 1 Changes in the transmission rate of the electronic device

accommodate a wide range of requirements for next-generation high-speed and high-frequency applications with the help of our own proprietary resin property modification technology.

4 Technical details

1. MCL-LW-900G design concept

We developed a resin with a low dielectric constant and high heat resistance with the help of our own proprietary resin property modification technology, and we used it for MCL-LW-900G. Then, we selected halogen-free flame retardant with high thermal decomposition temperature, together with small drop in glass transition temperature (Tg) and dielectric constant. We also used copper foil having a finely roughened surface to reduce conductor losses.

2. General characteristics of MCL-LW-900G

General characteristics of MCL-LW-900G are shown in **Table 1**. MCL-LW-900G (E-glass cloth, copper foil: RT foil) has Dk = 3.57 and Df = 0.0044 Dk at 10 GHz. MCL-LW-910G (low-dielectric glass cloth, copper foil: HVLP foil) shows Dk = 3.32 and Df = 0.0028.

Further, MCL-LW-900G shows excellent heat resistance such as TMA Tg: approx. 200°C and T-300 min. ≥ 60.

Table 1 General properties of MCL-LW-900G/910G

| Item | | Unit | LW-900G | LW-910G | FX-2 | Teflon material |
|--------------------------------------|-------------|--------|----------------------|--|---------------|--|
| Resin system | | — | Thermosetting | | Thermosetting | Thermoplastic |
| Glass type | | — | E-glass | Low Dk glass | E-glass | E-glass |
| Flame retardant chemicals | | — | Halogen free | | Halogen | — |
| Dk (JPCA-TM001) | 10 GHz | — | 3.57 | 3.32 | 3.45 | 2.62 |
| Df (JPCA-TM001) | 10 GHz | — | 0.0044* ¹ | 0.0035* ¹ 0.0028* ² | 0.0058 | 0.0038 |
| Copper foil peeling strength (18 μm) | RTF HVLP | kN/m | 0.75 0.63 | 0.75 0.63 | 0.60 — | 1.2 (general purpose copper foil) — |
| Tg | TMA | °C | 198 | 198 | 185 | 30 |
| CTE | XY | ppm/°C | 13 | 13 | 15 | 18 |
| | Z (α1) | | 40 | 40 | 47 | 105 |
| | Z (α2) | | 250 | 250 | 110 | 310 |
| Resistance to soldering heat testing | 288°C | s | > 300 | > 300 | > 300 | > 300 |
| T-300 | TMA | min | > 60 | > 60 | > 60 | — |
| Flame resistance | UL-94 | — | V-0 | V-0 | V-0 | V-0 |
| Reliability (CAF, IST, etc.) | — | — | Good | Good | Good | — |

*1, *2 Values calculated from the results of measured energy loss-rate (RT foil: Rz ≈ 3 μm, HVLP foil: Rz ≈ 1.2 μm).

3. Transmission characteristics of MCL-LW-900G

Results of measured transmission loss of MCL-LW-900G below 20 GHz are shown in **Figure 2**. MCL-LW-900G has excellent transmission characteristics as shown by MCL-LW-910G (HVLP foil) with transmission loss of 32.4 dB/m at 20 GHz which is lower by 15 dB/m than that of MCL-FX-2, suggesting that it can contribute to the reduction of transmission loss.

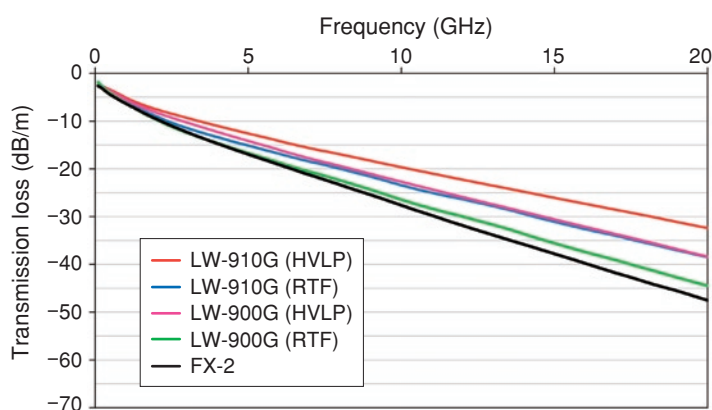


Figure 2 Transmission loss measurement results

5 Future Business Development

- Development of BU film for vehicle mounted millimeter wave radar

【Reference】

- 1) Kazutoshi Danjobara, *Preliminary Draft Collection of JPCA Show2014NPI Presentation*, pp.21-23